

General Description

The SJD30N060 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- Load switch
- PWM applications
- Power management

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	30	V
R _{DS(ON)_TYP}	6.2	mΩ
ID	55	А
Q _G	21.2	nC





Schematic Diagram

TO-252(DPAK) top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD30N060	SJD30N060	TO-252	Tape	/	١	2500 Pcs

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	30	V
V _{GS}	Gate-Source Voltage (V _{DS} =0V)	±20	V
I-	Drain Current-Continuous(Tc=25°C)	55	А
lo	Drain Current-Continuous(T _c =100 $^{\circ}$ C)	34	А
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	220	А
D	Maximum Power Dissipation(Tc=25 $^\circ\!\mathbb{C}$)	38	W
PD	Maximum Power Dissipation(Tc=100°C)	15	W
E _{AS}	Avalanche energy (Note 2)	72	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
Rejc	Thermal Resistance, Junction-to-Case		3.3	°C/W



Table 3. Electrical Characteristics (T_J=25 $^{\circ}$ C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250µA	30			V
		V _{DS} =30V, V _{GS} =0V TJ=25℃			1	μA
IDSS	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =125℃			100	μA
Igss	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1		2.5	V
g fs	Forward Transconductance	V _{DS} =5V, I _D =20A		28		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A T _J =25℃		6.2	8.1	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =20A T _J =25℃		8.1	10.8	mΩ
Dynamic Chara	cteristics		L			
Ciss	Input Capacitance			1062		pF
Coss	Output Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		130		pF
Crss	Reverse Transfer Capacitance			114		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.53		Ω
Switching Para	meters					
t _{d(on)}	Turn-on Delay Time			6.4		nS
tr	Turn-on Rise Time	V _{GS} =10V, V _{DS} =15V, R _L =1.5Ω, R _{GEN} =6Ω		346		nS
$t_{d(off)}$	Turn-Off Delay Time			19.4		nS
t _f	Turn-Off Fall Time			9.8		nS
Qg	Total Gate Charge			21.2		nC
Q _{gs}	Gate-Source Charge	V _{GS} =10V, V _{DS} =15V, I _D =20A		2.32		nC
Q _{gd}	Gate-Drain Charge			4.24		nC
Source-Drain D	iode Characteristics			1		
I _{SD}	Source-Drain Current (Body Diode)				55	Α
Vsd	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A		1	1.2	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=40V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

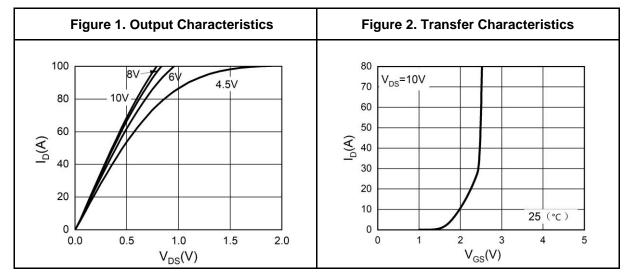
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

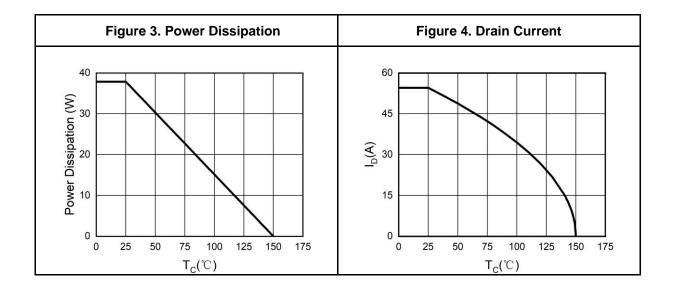


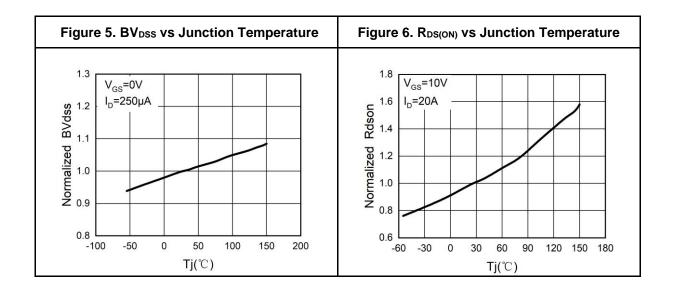
SJD30N060

30V N-Channel Trench Power MOSFET

Typical Electrical And Thermal Characteristics (Curves)





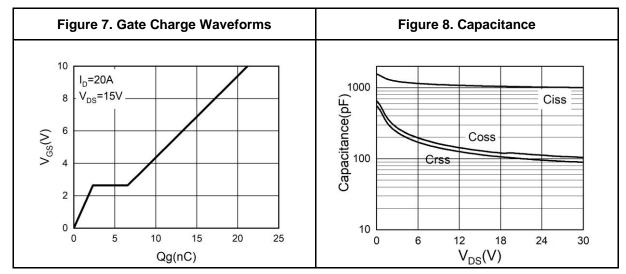


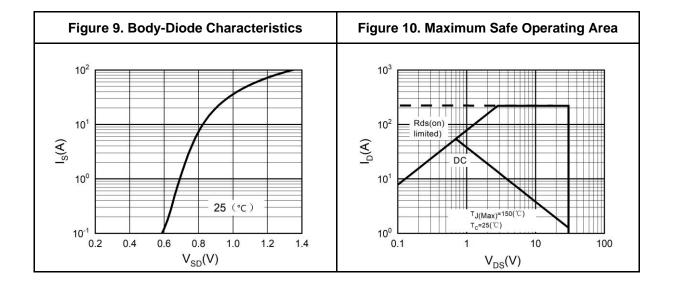


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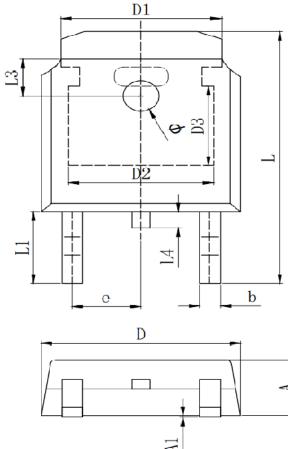
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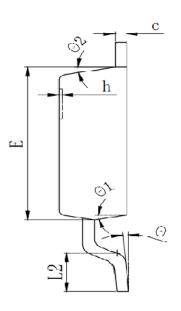






TO-252 Package Information





Symbol	Dimensions In Millimeters					
Symbol	Min.	Тур.	Max.			
A	2.200	2.300	2.400			
A1	0.000		0.127			
b	0.640	0.690	0.740			
c(电镀后)	0.460	0.520	0.580			
D	6.500	6.600	6.700			
D1		5.334 REF				
D2		4.826 REF				
D3	3.166 REF					
E	6.000	6.100	6.200			
е		2.286 TYP				
h	0.000	0.100	0.200			
L	9.900	10.100	10.300			
L1		2.888 REF				
L2 1.400		1.550	1.700			
L3		1.600 REF				
L4	0.600	0.800	1.000			
Φ	1.100	1.200	1.300			
θ	0°		8°			
θ1		9° TYP				
θ2		9° TYP				



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